



RESPONSE UNDER 37 C.F.R. § 1.116

EXPEDITED PROCEDURE – Art Unit 2827

Attorney Docket No. 108298531US

Express Mail Label EV139302897US

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: David J. Corisis *et al.*

APPLICATION No.: 09/644,476

FILED: August 23, 2000

FOR: **METHOD AND APPARATUS FOR
DECOUPLING CONDUCTIVE PORTIONS
OF A MICROELECTRONIC DEVICE
PACKAGE**

EXAMINER: David E. Graybill

ART UNIT: 2827

CONF. No: 2634

TECHNOLOGY CENTER 2800

DEC 26 2002

RECEIVED

Amendment Under 37 C.F.R. § 1.116

Box AF
Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

The present communication responds to the Office Action dated September 19, 2002, in the above-identified application. Please amend the application as follows. The attached Appendix presents a marked-up version of the changes made to the claims by the current amendment.

In the Claims:

Please cancel claims 13, 15, 17-37 and 39. Please amend claims 1, 14 and 16 as follows. Please add new claims 62-67. Following is a complete listing of the claims pending in the application, as amended:

1. (Amended) A method for packaging a microelectronic substrate, comprising:

positioning a conductive member at least proximate to the microelectronic substrate, the conductive member having first and second neighboring